

Title (en)

MATRIX LIQUID FOR PRODUCING A CHIP REMOVAL SUSPENSION, AND USED AS A LUBRICATING OR MACHINING LIQUID

Title (de)

MATRIXFLÜSSIGKEIT ZUR HERSTELLUNG EINER ZERSpanungSSUSPENSION SOWIE ALS SCHMIER- ODER BEARBEITUNGSFLÜSSIGKEIT

Title (fr)

LIQUIDE MATRICIEL SERVANT A PRODUIRE UNE SUSPENSION D'ENLEVEMENT DE COPEAUX, UTILISE EN TANT QUE LIQUIDE LUBRIFIANT OU LIQUIDE DE TRAITEMENT

Publication

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Application

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Abstract (en)

[origin: WO2005123888A1] The invention relates to a matrix liquid for producing chip removal suspensions, a chip removal suspension produced using said matrix liquid, and a method for fractioning the chip removal suspension used. The invention also relates to a homogeneous mixture consisting of a polymer or various polymers and water, that can be especially advantageously used in all technical applications in which lubricating properties are required from a liquid. According to the invention, a mixture of water and a thickening agent or at least one polymer is used as the matrix or lubricating liquid. The cutting grains can be easily and rapidly separated from a used chip removal suspension that has been produced using said matrix liquid, in order to be reused. Less process water is required and the process water can be easily biologically purified, as it does not have to be rid of an alcohol content in a complex manner.

IPC 8 full level

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